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PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

IN RE APPLICATION OF: Whonchee Lee *et al.*

APPLICATION No.: 09/888,002

FILED: June 21, 2001

FOR: **METHODS AND APPARATUS FOR
ELECTRICALLY AND/OR CHEMICALLY-
MECHANICALLY REMOVING
CONDUCTIVE MATERIAL FROM A
MICROELECTRONIC SUBSTRATE**

EXAMINER: Dung V. Nguyen

ART UNIT: 3723

CONF. No: 9049

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TECHNOLOGY CENTER R3700

Amendment Under 37 C.F.R. § 1.111

Box Non-Fee Amendment
Assistant Commissioner for Patents
Washington, D.C. 20231

Sir:

The present communication responds to the Office Action dated December 2, 2002 in the above-identified application. Please amend the application as follows. The attached Appendix presents a marked-up version of the changes made to the claims by the current amendment.

In the Claims:

Please amend claims 25, 26 and 29 as follows. Please cancel claims 36-64 and please add new claims 108-111. Following is a complete listing of the claims pending in the application, as amended:

1. A method for removing electrically conductive material from a face surface of a microelectronic substrate, comprising:
- spacing a first conductive electrode apart from the microelectronic substrate;
 - spacing a second conductive electrode apart from the microelectronic substrate;